MHT

Introduction

MHT is a Grade 3 (HTE) copper foil with high temperature, heat resistance treatment designed for Polyimide and other high Tg substrates and low loss resins.

Benefits

- Enhanced bonding treatment for Polyimide and other high Tg resins, results in improved adhesion
- MHT is low profile, for foil thickness less than 70 microns, for finer lines and consistent etching
- Improves PWB performance

Typical Physical Characteristics

Oak-Mitsui foils meet all requirements of IPC-4562 and are produced with the patented "AT" resin resistant treatment.

Nominal Thickness Area Weight		microns oz/ft²	18 1/2	35 1	70 2
Tensile	ambient 180°C	Kpsi Kpsi	60 30	55 30	52.5 30
Elongation	ambient 180°C	%E %E	8 8	15 8	20 8
Roughness	drum matte	Ra Rmax	10 200	10 285	10 450
Peel Strength B Polyimide	Matte	lbs/in	5.5	7	7

The information contained in this specification is not intended to and does not create any warranties, express or implied, including any warranty of merchantability or fitness for a particular purpose. The actual performance of Mitsui materials will vary according to the customer's application.